

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a semiconductor die and a multi-level interconnect structure that has a first insulating layer formed on the die, conductive horizontal bodies, each of which is connected to a respective bonding pad of the die and has an extension formed on the first insulating layer, a second insulating layer formed on the first insulating layer, and conductive vertical bodies, each of which is connected to the extension of a respective conductive horizontal body and extends through the second insulating layer.